

ABSTRACT OF THE DISCLOSURE

A semiconductor substrate is mounted on a semiconductor alignment apparatus. A chip alignment step is performed to center a central chip on the semiconductor substrate with respect to the semiconductor alignment apparatus, and to store the coordinates thereof. A semiconductor substrate alignment is performed to virtually align the semiconductor substrate with the semiconductor alignment apparatus. At this time, coordinates of a chip adjacent to the central chip and of a number of chips in a peripheral region of the semiconductor substrate are stored in the alignment apparatus. In addition, at least two templates are located in the central chip, and images and coordinates of the templates are stored in the semiconductor alignment apparatus during the semiconductor substrate alignment.